



## Materials Declaration Form

<b>IPC</b>	<b>1752</b>	<b>Version</b>	<b>2</b>
<b>Form Type *</b>	<b>Distribute</b>		
<b>Sectionals *</b>	<b>Material Info</b> <b>Manufacturing Info</b>	<b>Subsectionals *</b>	<b>A-D</b>
<i>* : Required Field</i>			

<b>Supplier Information</b>			
<b>Company Name *</b>	<b>STMicroelectronics</b>	<b>Response Date *</b>	<b>2018-06-25</b>
<b>Contact Name *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Authorized Representative *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	<b>Rossana Bonaccorso</b>	<b>Representative Title</b>	<b>ADG MD Champion</b>
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	<b>true</b>	<b>Legal Declaration *</b>	<b>Standard</b>
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	C8VY*UR55BX1	A	0959	2018-06-25
Amount	UoM	Unit type	ST ECOPACK Grade	
263.00	mg	Each	ECOPACK2	
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy		
NA	NiPdAuAg	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	10-10-1	64	gull wing	
Comment	Package: LQFP 64 LEADS 10X10X1.4 EP UP - MDF valid for CPs: FDA802B-VYY - FDA802B-VYT			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
Exemption Id.	Description

QueryList : California Prop65 list, dated 25th May 2018			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.61	Leadframe	2304
Cobalt	0.002	Die	8

QueryList : REACH-15th January 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	CBVY*UR55BX1					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	19.553	mg	supplier	die	Silicon (Si)	7440-21-3		17.764	mg	908491	67548
				supplier	metallization	Copper (Cu)	7440-50-8		1.210	mg	61879	4601
				supplier	metallization	Cobalt (Co)	7440-48-4		0.002	mg	102	8
				supplier	metallization	Platinum (Pt)	7440-06-4		0.075	mg	3835	285
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	51	4
				supplier	metallization	Tungsten (W)	7440-33-7		0.056	mg	2864	213
				supplier	Passivation	Silicon Nitride	12033-89-5		0.048	mg	2455	183
				supplier	Passivation	Silicon Oxide	7631-86-9		0.193	mg	9870	734
				supplier	polymer die coating	Polyimide AH 1200	Proprietary		0.204	mg	10453	777
				Leadframe	M-004 Copper and its alloys	100.226	mg	supplier	alloy	Copper (Cu)	7440-50-8	
supplier	alloy	Iron (Fe)	7439-89-6						0.100	mg	997	380
supplier	alloy	Iron Phosphide (FeP)	26508-33-8						0.030	mg	299	114
supplier	metallization	Nickel (Ni)	7440-02-0						0.606	mg	6046	2304
supplier	metallization	Palladium (Pd)	7440-05-3						0.020	mg	200	76
supplier	metallization	Gold (Au)	7440-57-5						0.018	mg	180	61
supplier	metallization	Silver (Ag)	7440-22-4						0.018	mg	180	68
supplier	glue	Silver (Ag)	7440-22-4						4.126	mg	895011	15688
Die attach		4.610	mg	supplier	glue	Isobornyl Methacrylate	7534-94-3		0.346	mg	75054	1316
				supplier	glue	Bismaleimide resin	35325-39-4		0.138	mg	29935	525
Bonding wires	M-011 Other inorganic materials	2.990	mg	supplier	wire	Copper (Cu)	7440-50-8		2.990	mg	1000000	11369
Encapsulation	M-011 Other inorganic materials	135.621	mg	supplier	mold compound	Silica, vitreous	60676-86-0		117.176	mg	863996	445536
				supplier	mold compound	Epoxy Resin	25068-38-6		10.172	mg	75003	38677
				supplier	mold compound	Phenol Resin	29690-82-2		6.781	mg	50000	25783
				supplier	mold compound	3-Mercaptopropyl trimethoxysilane	4420-74-0		0.678	mg	4999	2578
				supplier	mold compound	Quartz	14808-60-7		0.407	mg	3001	1548
				supplier	mold compound	Carbon black	1333-86-4		0.407	mg	3001	1548